DD-12864WE-2A

PRODUCT SPECIFICATION

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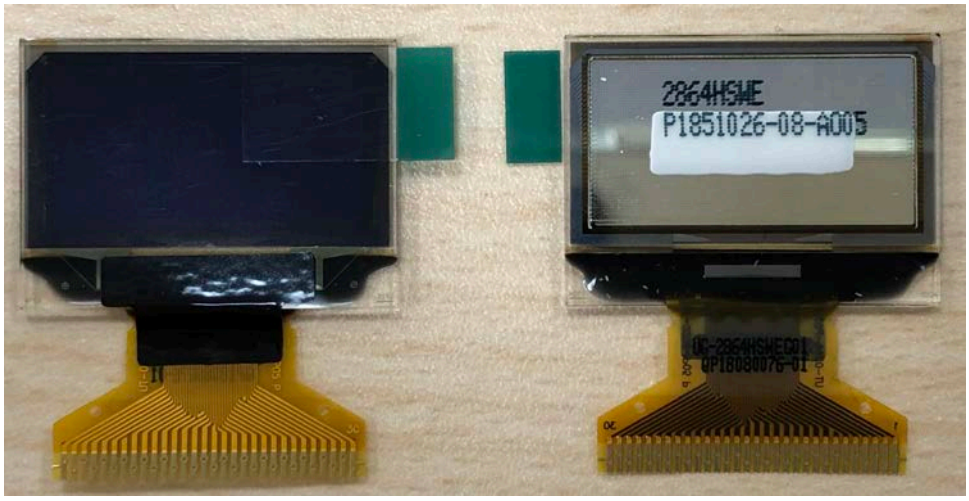

Customer's Approval	
Signature	*Date*

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Revision History

VERSION	DATE	DESCRIPTION	AUTHOR
1.0	Mar 19, 2020	Initial Released	Chi Huang

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1. General Description

1.1 Introduction

This is 0.96” Size passive matrix OLED display with Anti-Glare polarizer. This display comes in white monochrome area colour and all-round view, has a resolution of 128 x 64, and the display module supports 8-bit 68XX/80XX Parallel, 3-/4-wire SPI and I^2C interface.

1.2 Main Features

Item	Contents
Display Format	128 x 64 Dots
Colour	White Monochrome
Overall Dimensions	26.70 (W) x 19.26 (H) x 1.45 (D) mm
Surface Treatment	Anti-Glare
Viewing Area	23.744 (W) x 12.864 (H) mm
Active Area	21.744 (W) x 10.864 (H) mm
Display Mode	Passive Matrix (0.96”)
Duty ratio	1/64
Display Driver IC	SSD1306
Operating temperature	-40°C ~ +70°C
Storage temperature	-40°C ~ +85°C
ROHS	Compliant to RoHS 2.0

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2. Mechanical Specification

2.1 Mechanical Characteristics

Item	Characteristic	Unit
Display Format	128 x 64	Dots
Overall Dimensions	26.70 (W) x 19.26 (H) x 1.45 (D)	mm
Viewing Area	23.744 (W) x 12.864 (H)	mm
Active Area	21.744 (W) x 10.864 (H)	mm
Dot Size	0.154 (W) x 0.154 (H)	mm
Dot Pitch	0.170 (W) x 0.170 (H)	mm
Weight	1.54± 10%	g
IC Controller/Driver	SSD1306	

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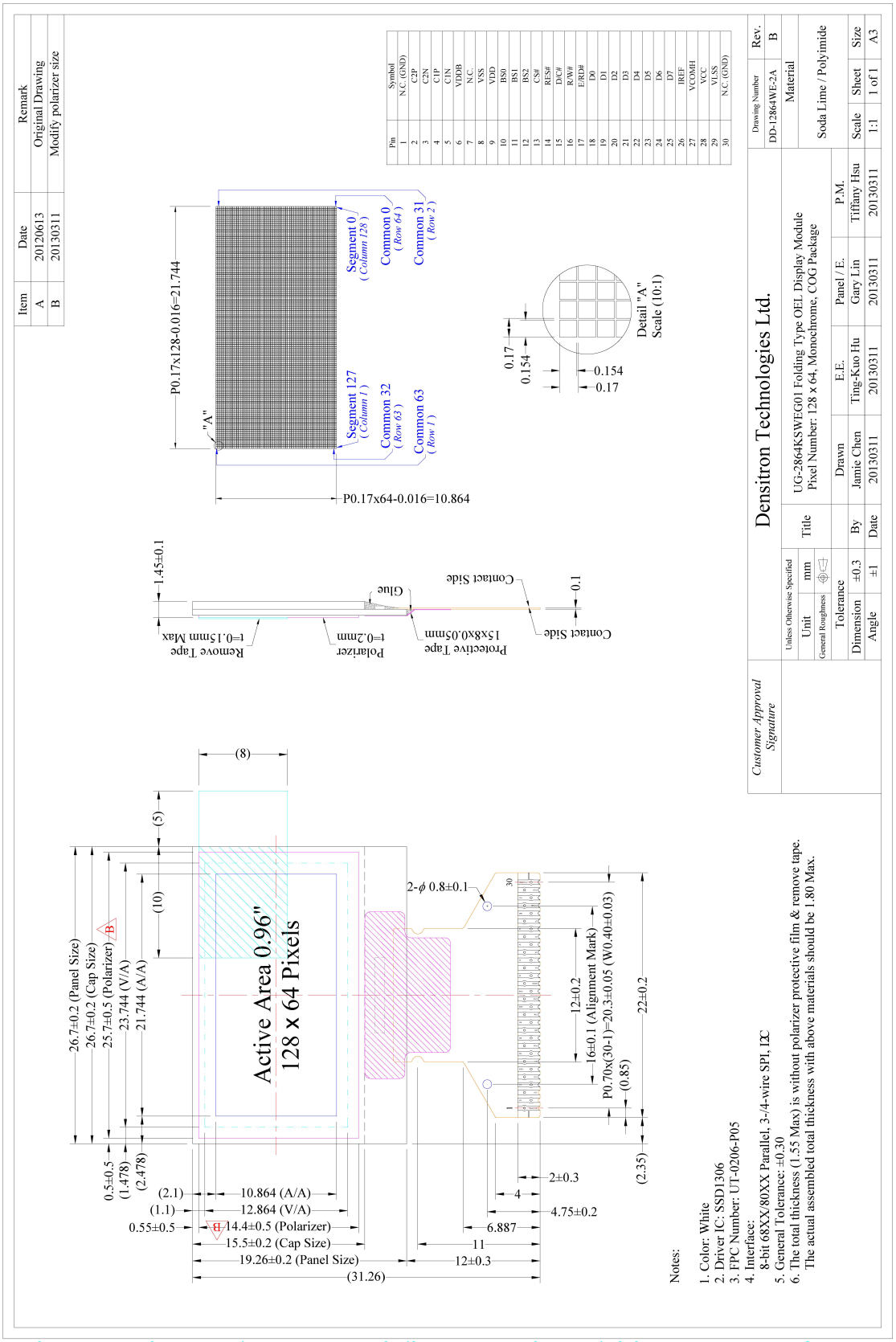
2.2 Mechanical Drawing



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3. Electrical Specification OLED

3.1 Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Note
Supply Voltage for Logic	V_{DD}	-0.3	4	V	1, 2
Supply Voltage for Display	V_{cc}	0	11	V	
Supply Voltage for DC/DC	V_{DDB}	-0.3	5	V	
Operating Temperature	T_{OP}	-40	70	°C	-
Storage Temperature	T_{STG}	-40	85	°C	3
Life Time (100 cd/m^2)	-	10,000	-	hour	4
Life Time (80 cd/m^2)	-	30000	-	hour	-
Life Time (60 cd/m^2)	-	50000	-	hour	

Note 1: All the above voltages are on the basis of "V_{SS} = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section 3.2 "DC Electrical Characteristics OLED" and Section 4. "Optical Characteristics OLED". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate.

Note 3: The defined temperature ranges do not include the polarizer. The maximum withstood temperature of the polarizer should be 80°C

Note 4: V_{CC}=9.0V, T_a=25°C, 50% Checkerboard.
Software configuration follows section 5.5.1 Initialization.
End of lifetime is specified as 50% of initial brightness reached. The average operating lifetime at room temperature is estimated by the accelerated operation at high temperature conditions.

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3.2 DC Electrical Characteristics OLED

3.2.1 V_{CC} Supplied Externally

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Supply Voltage for Logic	V_{DD}	-	1.65	2.8	3.3	V	-
Supply Voltage for Display (Supplied Externally)	V_{CC}	Internal DC/DC Disable	8.5	9.0	9.5	V	1
High Level Input	V_{IH}	-	0.8 x V_{DD}	-	V_{DD}	V	-
Low Level Input	V_{IL}	-	0	-	0.2 x V_{DD}	V	-
High Level Output	V_{OH}	I_{OUT}=100μA, 3.3MHz	0.9 x V_{DD}	-	V_{DD}	V	-
Low Level Output	V_{OL}	I_{OUT}=100μA, 3.3MHz	0	-	0.1 x V_{DD}	V	-
Operating Current for V_{DD}	I_{DD}	-	-	180	300	μA	-
Operating Current for V_{CC} (V_{CC} Supplied Externally)	I_{CC}	-	-	5.7	7.1	mA	2
		-	-	8.5	10.6	mA	3
		-	-	15.3	19.1.	mA	4
Sleep Mode Current for V_{DD}	$I_{DD, SLEEP}$	-	-	1	5	μA	-
Sleep Mode Current for V_{CC}	$I_{CC, SLEEP}$	-	-	2	10	μA	-

Note 1: Brightness (L_{br}) and Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.

Note 2: V_{DD} = 2.8V, V_{CC} = 9.0V, 30% Display Area Turn on.

Note 3: V_{DD} = 2.8V, V_{CC} = 9.0V, 50% Display Area Turn on.

Note 4: V_{DD} = 2.8V, V_{CC} = 9.0V, 100% Display Area Turn on.

*Software configuration follows section 5.5.1 Initialization

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3.2.2 V_{CC} Generated by Internal DC/DC Circuit

Item	Symbol	Condition	Min	Typ	Max	Unit	Note
Supply Voltage for Logic	V_{DD}	-	1.65	2.8	3.3	V	-
Supply Voltage for DC/DC	V_{DDB}	Internal DC/DC Enable	3.0	-	4.2	V	-
Supply Voltage for Display (Generated by Internal DC/DC)	V_{CC}	Internal DC/DC Enable	7.0	7.5	8.0	V	1
High Level Input	V_{IH}	-	0.8 x V_{DD}		V_{DD}	V	-
Low Level Input	V_{IL}	-	0		0.2 x V_{DD}	V	-
High Level Output	V_{OH}	I_{OUT}=100μA, 3.3MHz	0.9 x V_{DD}	-	V_{DD}	V	-
Low Level Output	V_{OL}	I_{OUT}=100μA, 3.3MHz	0	-	0.1 x V_{DD}	V	-
Operating Current for V_{DD}	I_{DD}	-	-	180	300	μA	-
Operating Current for V_{DDB} (V_{CC} Generated by Internal DC/DC)	I_{DDB}	-	-	12.5	15.6	mA	2
		-	-	17.8	22.3	mA	3
		-	-	27.9	34.9	mA	4
Sleep Mode Current for V_{DD}	$I_{DD, SLEEP}$	-	-	1	5	μA	-
Sleep Mode Current for V_{DDB}	$I_{DDB, SLEEP}$	-	-	2	10	μA	-

Note 1: Brightness (L_{br}) and Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.

Note 2: V_{DD} = 2.8V, V_{DDB} = 3.5V, V_{CC} Generated by Internal DC/DC, 30% Display Area Turn on.

Note 3: V_{DD} = 2.8V, V_{DDB} = 3.5V, V_{CC} Generated by Internal DC/DC, 50% Display Area Turn on.

Note 4: V_{DD} = 2.8V, V_{DDB} = 3.5V, V_{CC} Generated by Internal DC/DC, 100% Display Area Turn on.

*Software configuration follows section 5.5.2 Initialization

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3.3 Interface Pin Assignment

<table>
<tr><th>No.</th><th>Symbol</th><th>I/O</th><th>Function</th></tr>
<tr><td>1</td><td>NC (GND)</td><td>-</td><td>-</td></tr>
<tr><td>2 / 3
4 / 5</td><td>C2P / C2N
C1P / C1N</td><td>I</td><td>Positive Terminal of the Flying Inverting Capacitor
Negative Terminal of the Flying Boost Capacitor
The charge-pump capacitors are required between the terminals.
They must be floated when the converter is not used.</td></tr>
<tr><td>6</td><td>VDDB</td><td>P</td><td>Power Supply for DC/DC Converter Circuit
This is the power supply pin for the internal buffer of the DC/DC voltage converter.
It must be connected to external source when the converter is used. It should be connected to V_{DD} when the converter is not used.</td></tr>
<tr><td>7</td><td>NC</td><td>-</td><td>Reserved Pin
The N.C. pin between function pins are reserved for compatible and flexible design.</td></tr>
<tr><td>8</td><td>VSS</td><td>P</td><td>Ground of Logic Circuit
This is a ground pin. It acts as a reference for the logic pins. It must be connected to external ground.</td></tr>
<tr><td>9</td><td>VDD</td><td>P</td><td>Power Supply for Logic
This is a voltage supply pin. It must be connected to external source.</td></tr>
<tr><td>10
11
12</td><td>BS0
BS1
BS2</td><td>I</td><td>Communicating Protocol Select
These pins are MCU interface selection input. See the following table:
<table>
<tr><th></th><th>BS0</th><th>BS1</th><th>BS2</th></tr>
<tr><td>I2C</td><td>0</td><td>1</td><td>0</td></tr>
<tr><td>3-wire SPI</td><td>1</td><td>0</td><td>0</td></tr>
<tr><td>4-wire SPI</td><td>0</td><td>0</td><td>0</td></tr>
<tr><td>8-bit 68XX Parallel</td><td>0</td><td>0</td><td>1</td></tr>
<tr><td>8-bit 80XX Parallel</td><td>0</td><td>1</td><td>1</td></tr>
</table></td></tr>
<tr><td>13</td><td>CS#</td><td>I</td><td>Chip Select
This pin is the chip select input. The chip is enabled for MCU communication only when CS# is pulled low.</td></tr>
<tr><td>14</td><td>RES#</td><td>O</td><td>Power Reset for Controller and Driver
This pin is reset signal input. When the pin is low, initialization of the chip is executed.
Keep this pin pull high during normal operation.</td></tr>
<tr><td>15</td><td>D/C#</td><td>P</td><td>Data/Command Control
This pin is Data/Command control pin. When the pin is pulled high, the input at D7~D0 is treated as display data. When the pin is pulled low, the input at D7~D0 will be transferred to the command register.
When the pin is pulled high and serial interface mode is selected, the data at SDIN will be interpreted as data. When it is pulled low, the data at SDIN will be transferred to the command register. In I²C mode, this pin acts as SA0 for slave address selection.
For detail relationship to MCU interface signals, please refer to the Timing</td></tr>
</table>

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No.	Symbol	I/O	Function
			Characteristics Diagrams.
16	R/W#	I	**Read/Write Select or Write** This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as Read/Write (R/W#) selection input. Pull this pin to "High" for read mode and pull it to "Low" for write mode. When 80XX interface mode is selected, this pin will be the Write (WR#) input. Data write operation is initiated when this pin is pulled low and the CS# is pulled low. When serial or I^2C mode is selected, this pin must be connected to V_{SS}.
17	E/RD#	I	**Read/Write Enable or Read** This pin is MCU interface input. When interfacing to a 68XX-series microprocessor, this pin will be used as the Enable (E) signal. Read/write operation is initiated when this pin is pulled high and the CS# is pulled low. When connecting to an 80XX-microprocessor, this pin receives the Read (RD#) signal. Data read operation is initiated when this pin is pulled low and CS# is pulled low. When serial or I_2C mode is selected, this pin must be connected to V_{SS}.
18~25	D0~D7	I/O	**Host Data Input / Output Bus** These pins are 8-bit bi-directional data bus to be connected to the microprocessor's data bus. When serial mode is selected, D1 will be the serial data input SDIN and D0 will be the serial clock input SCLK. When I_2C mode is selected, D2 & D1 should be tired together and serve as SDA_{out} & SDA_{in} in application and D0 is the serial clock input SCL. Unused pins must be connected to V_{SS} except for D2 in serial mode.
26	IREF	I	**Current Reference for Brightness Adjustment** This pin is segment current reference pin. A resistor should be connected between this pin and V_{SS}. Set the current at 12.5µA maximum.
27	VCOMH	O	**Voltage Output High Level for COM Signal** This pin is the input pin for the voltage output high level for COM signals. A capacitor should be connected between this pin and V_{SS}.
28	VCC	P	**Power Supply for OEL Panel** This is the most positive voltage supply pin of the chip. A stabilization capacitor should be connected between this pin and V_{SS} when the converter is used. It must be connected to external source when the converter is not used.
29	VLSS	P	**Ground of Analog Circuit** This is an analog ground pin. It should be connected to V_{SS} externally.
30	N.C. (GND)	-	**Reserved Pin (Supporting Pin)** The supporting pins can reduce the influences from stresses on the function pins. These pins must be connected to external ground as the ESD protection circuit.

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3.4 Block Diagram

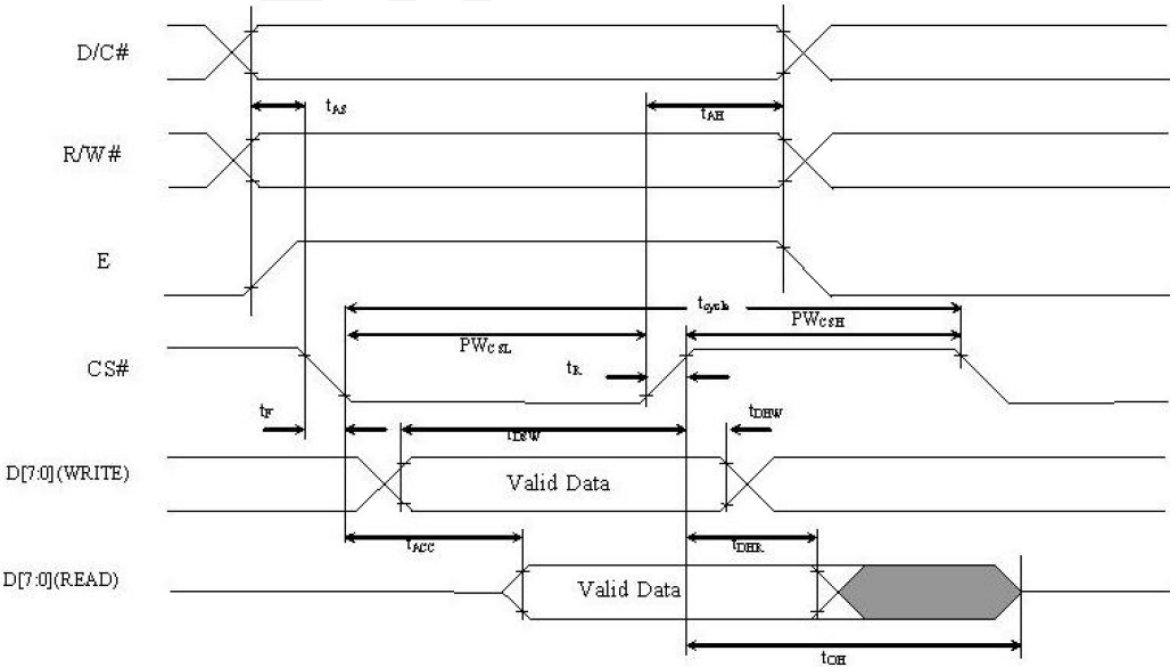
Please refer to section 5.4 Application circuit

3.5 Timing Characteristics

3.5.1 68XX-Series MPU Parallel Interface Timing Characteristics

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Clock Cycle Time	t_{CYCLE}	300	-	-	ns	-
Address Setup Time	t_{AS}	5	-	-	ns	-
Address Hold Time	t_{AH}	0	-	-	ns	-
Write Data Setup Time	t_{DSW}	40	-	-	ns	-
Write Data Hold Time	t_{DHW}	7	-	-	ns	-
Read Data Hold Time	t_{DHR}	20	-	-	ns	-
Output Disable Time	t_{OH}	-	-	70	ns	-
Access Time	t_{ACC}	-	-	140	ns	-
Chip Select Low Pulse Width (Read) Chip Select Low Pulse Width (Write)	PW_{CSL}	120 60	-	-	ns	-
Chip Select High Pulse Width (Read) Chip Select High Pulse Width (Write)	PW_{CSH}	60 60	-	-	ns	-
Rise Time	t_R	-	-	40	ns	-
Fall Time	t_F	-	-	40	ns	-

*(V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)



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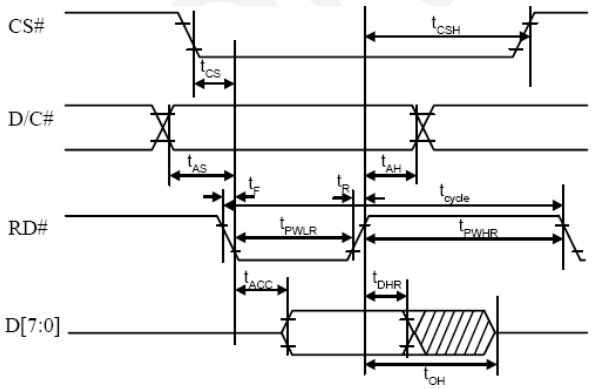
3.5.2 80XX-Series MPU Parallel Interface Timing Characteristics

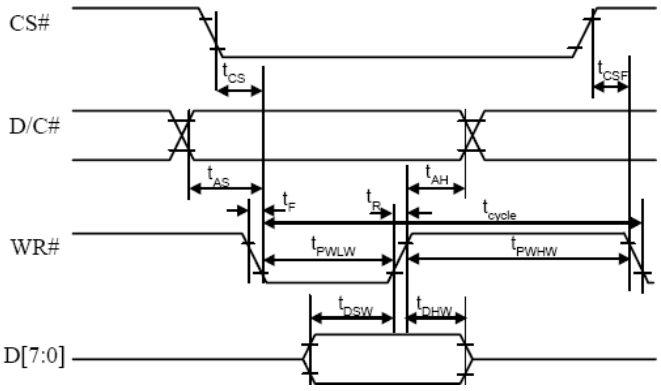
Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Clock Cycle Time	t_{CYCLE}	300	-	-	ns	-
Address Setup Time	t_{AS}	10	-	-	ns	-
Address Hold Time	t_{AH}	0	-	-	ns	-
Write Data Setup Time	t_{DSW}	40	-	-	ns	-
Write Data Hold Time	t_{DHW}	7	-	-	ns	-
Read Data Hold Time	t_{DHR}	20	-	-	ns	-
Output Disable Time	t_{OH}	-	-	70	ns	-
Access Time	t_{ACC}	-	-	140	ns	-
Read Low Time	t_{PWLR}	120	-	-	ns	-
Write Low Time	t_{PWLW}	60	-	-	ns	-
Read High Time	t_{PWHR}	60	-	-	ns	-
Write High Time	t_{PWHW}	60	-	-	ns	-
Chip Select Setup Time	t_{CS}	0	-	-	ns	-
Chip Select Hold Time to Read Signal	t_{CSH}	0	-	-	ns	-
Chip Select Hold Time	t_{CSF}	20	-	-	ns	-
Rise Time	t_R	-	-	40	ns	-
Fall Time	t_F	-	-	40	ns	-

*(V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)

Read Timing



Write Timing



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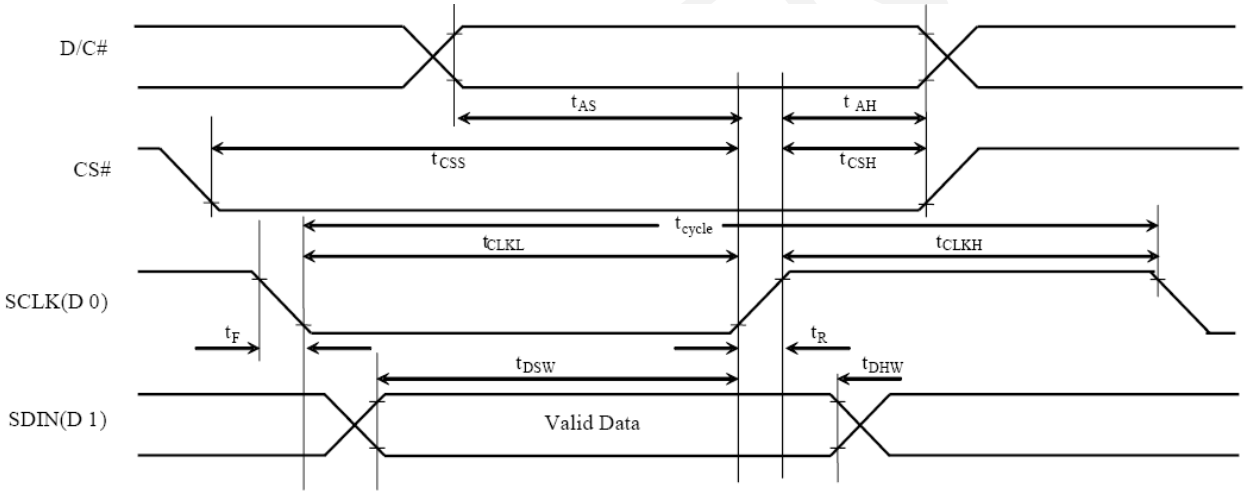
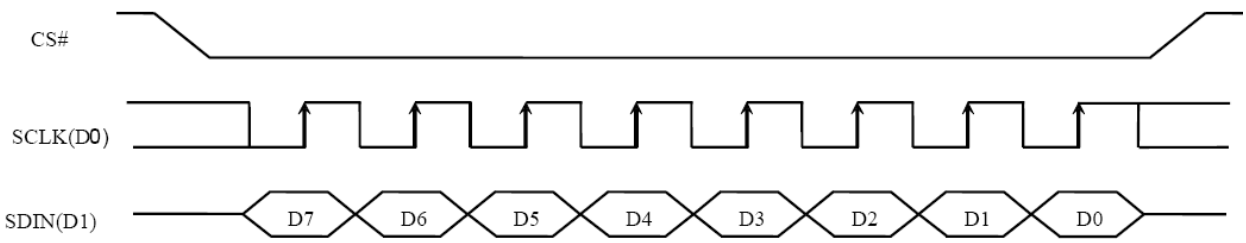
3.5.3 Serial Interface Timing Characteristics (4-wire SPI)

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Clock Cycle Time	t_{cycle}	100	-	-	ns	-
Address Setup Time	t_{AS}	15	-	-	ns	-
Address Hold Time	t_{AH}	15	-	-	ns	-
Chip Select Setup Time	t_{CSS}	20	-	-	ns	-
Chip Select Hold Time	t_{CSH}	10	-	-	ns	-
Write Data Setup Time	t_{DSW}	15	-	-	ns	-
Write Data Hold Time	t_{DHW}	15	-	-	ns	-
Clock Low Time	t_{CLKL}	20	-	-	ns	-
Clock High Time	t_{CLKH}	20	-	-	ns	-
Rise Time	t_R	-	-	40	ns	-
Fall Time	t_F	-	-	40	ns	-

*(V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)





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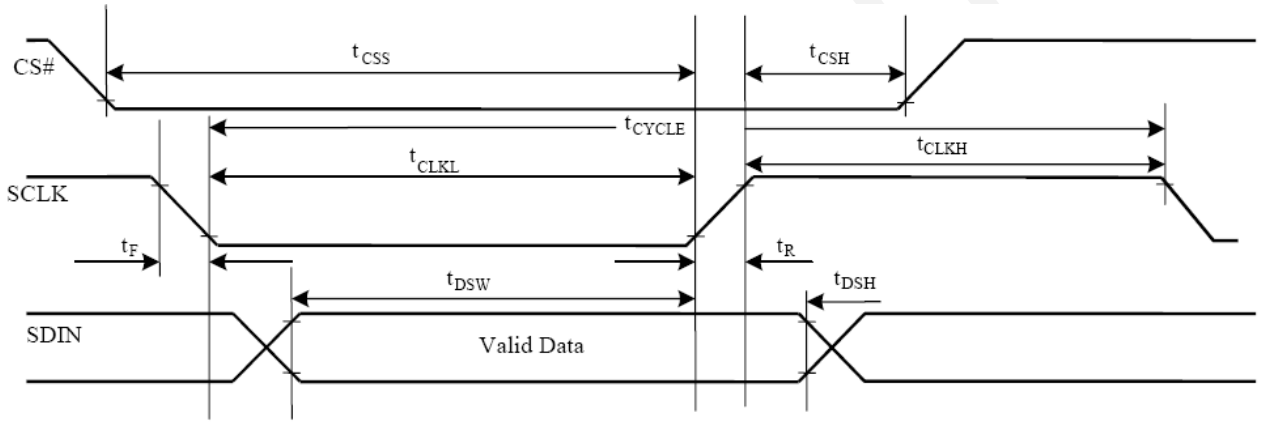
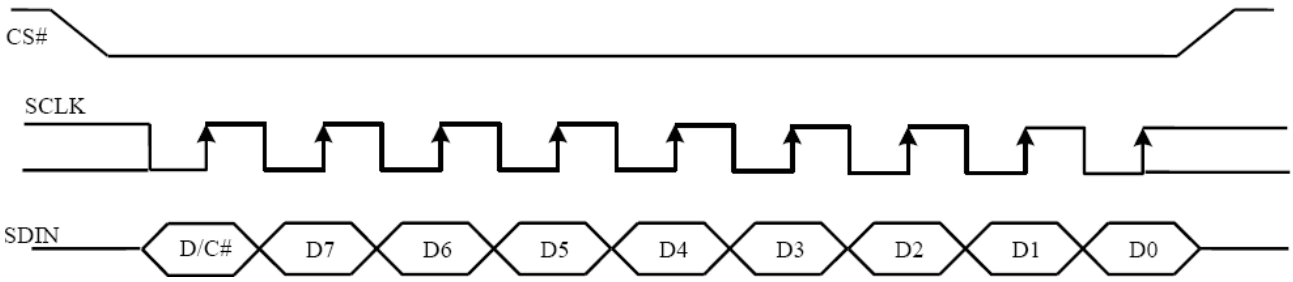
3.5.4 Serial Interface Timing Characteristics (3-wire SPI)

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Clock Cycle Time	t_{cycle}	100	-	-	ns	-
Chip Select Setup Time	t_{CSS}	20	-	-	ns	-
Chip Select Hold Time	t_{CSH}	10	-	-	ns	-
Write Data Setup Time	t_{DSW}	15	-	-	ns	-
Write Data Hold Time	t_{DHW}	15	-	-	ns	-
Clock Low Time	t_{CLKL}	20	-	-	ns	-
Clock High Time	t_{CLKH}	20	-	-	ns	-
Rise Time	t_R	-	-	40	ns	-
Fall Time	t_F	-	-	40	ns	-

*(V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)





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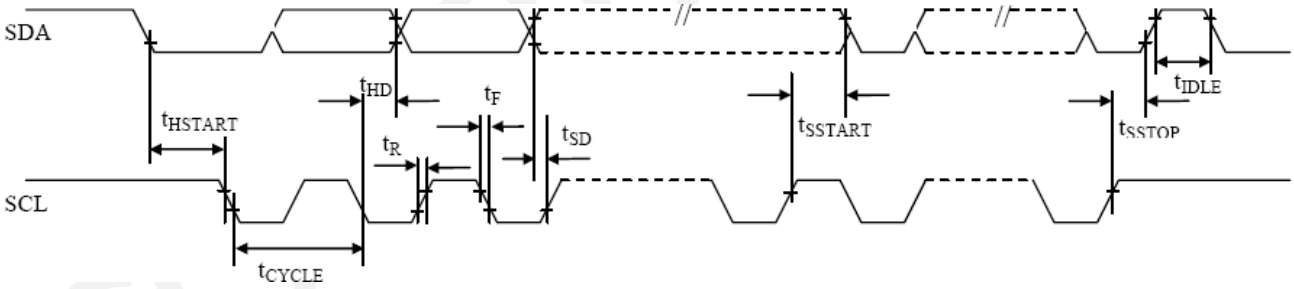
3.5.5 I²C Interface Timing Characteristics:

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Clock Cycle Time	t_{cycle}	2.5	-	-	µs	-
Start Condition Hold Time	t_{HSTART}	0.6	-	-	µs	-
Data Hold Time (for "SDA_{OUT}" Pin)	t_{HD}	0	-	-	ns	-
Data Hold Time (for "SDA_{IN}" Pin)	t_{HD}	300			ns	
Data Setup Time	t_{SD}	100	-	-	ns	-
Start Condition Setup Time (Only relevant for a repeated Start condition)	t_{SSTART}	0.6	-	-	µs	-
Stop Condition Setup Time	t_{SSTOP}	0.6	-	-	µs	-
Rise Time for Data and Clock Pin	t_R	-	-	300	ns	-
Fall Time for Data and Clock Pin	t_F	-	-	300	ns	-
Idle Time before a New Transmission can Start	t_{IDLE}	1.3	-	-	µs	-

*(V_{DD} - V_{SS} = 1.65V to 3.3V, T_a = 25°C)



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4. Optical Specification OLED

4.1 Optical Characteristics

Characteristics	Symbol	Conditions	Min	Typ	Max	Unit	Note
Brightness (V_{CC} Supplied Externally)	L_{br}	-	100	120	-	cd/m^2	1
Brightness (V_{CC} Generated by Internal DC/DC)	L_{br}	-	70	90	-	cd/m^2	2
C.I.E. (White)	(x)	C.I.E. 1931	0.24	0.27	0.30	-	-
	(y)		0.27	0.30	0.33		
Dark Room Contrast	CR	-	-	>10,000:1	-	-	-
Viewing Angle	-	-	-	Free	-	-	degree

*Optical measurement taken at (1) V_{DD} = 2.8V, V_{CC} = 9V & 7.5V.

*Software configuration follows Section 5.5.1 Initialization

Note 1: Brightness (L_{br}) and Supply Voltage for Display (V_{CC}) are subject to the change of the panel characteristics and the customer's request.

Note 2: V_{DD} = 2.8V, V_{CC} = 9.0V, 30% Display Area Turn on.

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5. Functional Specification OLED

5.1 Commands

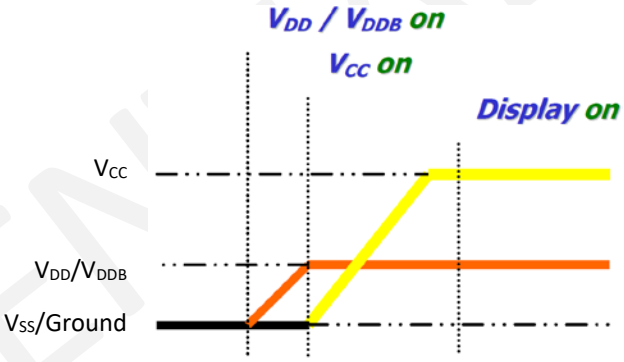
Refer to the Technical Manual for the SSD1306.

5.2 Power Down and Power Up Sequence

To protect OEL panel and extend the panel life time, the driver IC power up/down routine should include a delay period between high voltage and low voltage power sources during turn on/off. It gives the OEL panel enough time to complete the action of charge and discharge before/after the operation.

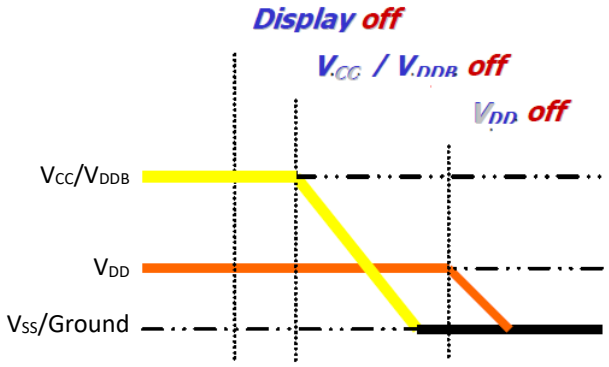
5.2.1 Power up Sequence

1. Power up V_{DD} / V_{DDB}
2. Send Display off command
3. Initialization
4. Clear Screen
5. Power up V_{CC}
6. Delay 100ms (When V_{CC} is stable)
7. Send Display on command



5.2.2 Power down Sequence

1. Send Display off command
2. Power down V_{CC} / V_{DDB}
3. Delay 100ms
   (When V_{CC} / V_{DDB} is reach 0 and panel is completely discharged)
4. Power down V_{DD}



Note:

1. Since an ESD protection circuit is connected between V_{DD} and V_{CC} inside the driver IC, V_{CC} becomes lower than V_{DD} whenever V_{DD} is ON and V_{CC} is OFF.
2. V_{CC} / V_{DDB} should be kept float (disable) when it is OFF.
3. Power Pins (V_{DD}, V_{CC}, V_{DDB}) can never be pulled to ground under any circumstance.
4. V_{DD} should not be power down before V_{CC} / V_{DDB} power down.

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5.3 Reset Circuit

When RES# input is low, the chip is initialized with the following status:

1. Display is OFF
2. 128 x 64 Display Mode
3. Normal segment and display data column and row address mapping (SEG0 mapped to column address 00h and COM0 mapped to row address 00h)
4. Shift register data clear in serial interface
5. Display start line is set at display RAM address 0
6. Column address counter is set at 0
7. Normal scan direction of the COM outputs
8. Contrast control register is set at 7Fh
9. Normal display mode (Equivalent to A4h command)

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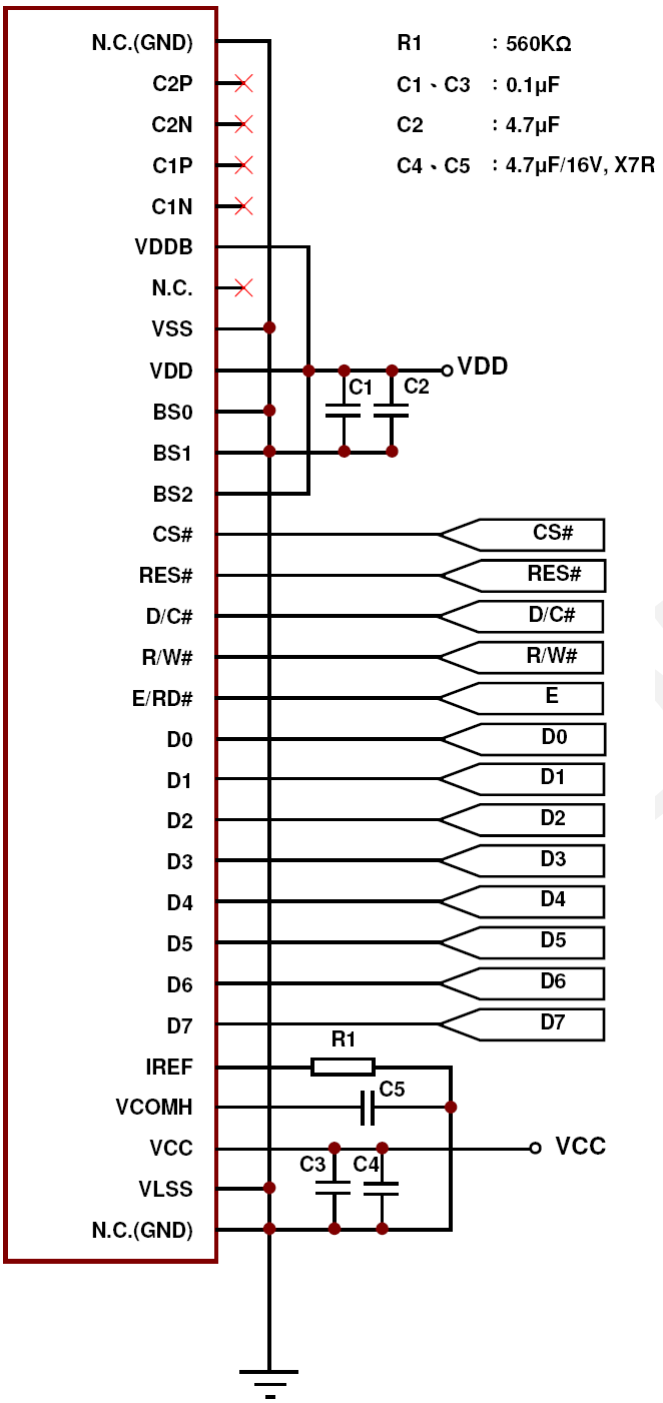
5.4 Application Circuit

5.4.1 68XX-Series MPU Parallel Interface and VCC Supplied Externally



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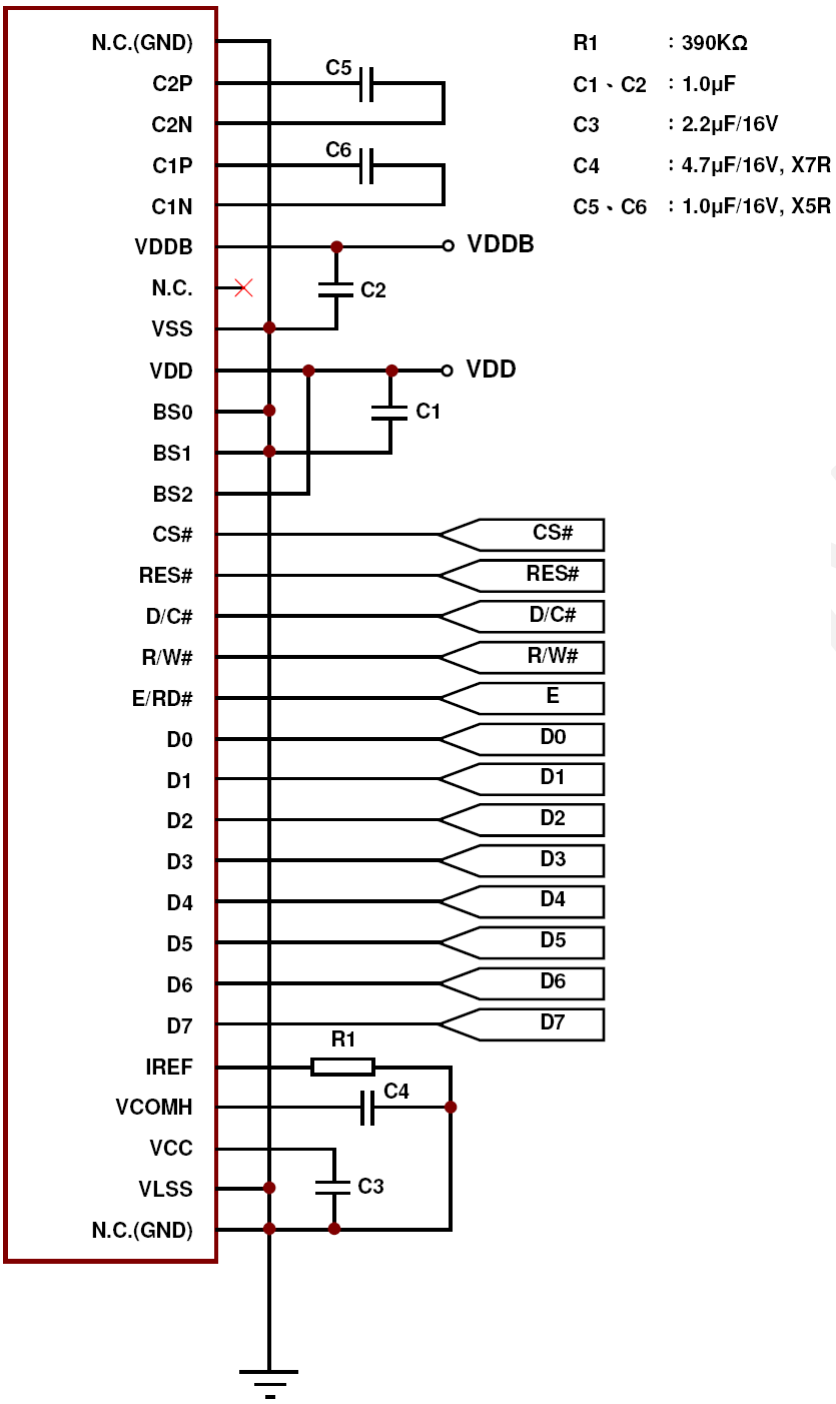
5.4.2 68XX-Series MPU Parallel Interface and VCC Generated by Internal DC/DC Circuit



R1	: 390KΩ
C1、C2	: 1.0μF
C3	: 2.2μF/16V
C4	: 4.7μF/16V, X7R
C5、C6	: 1.0μF/16V, X5R

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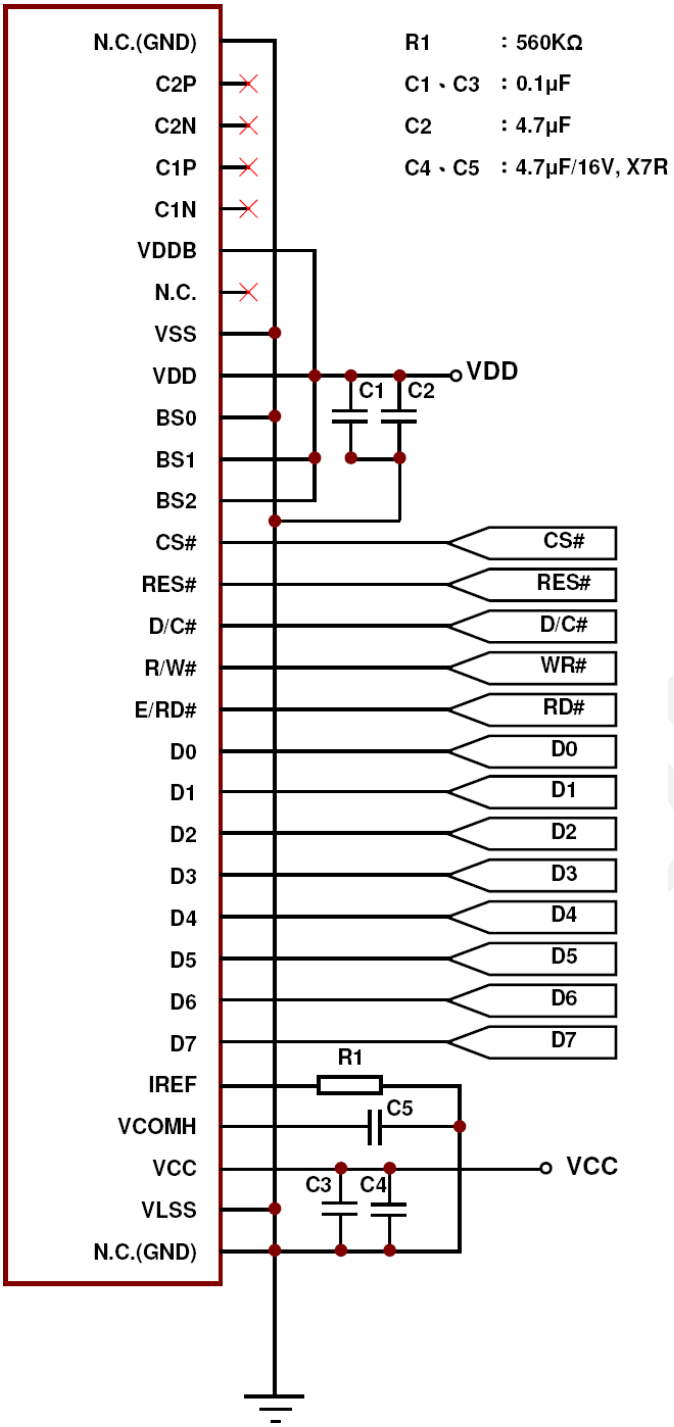
5.4.3 80XX-Series MPU Parallel Interface and VCC Supplied Externally



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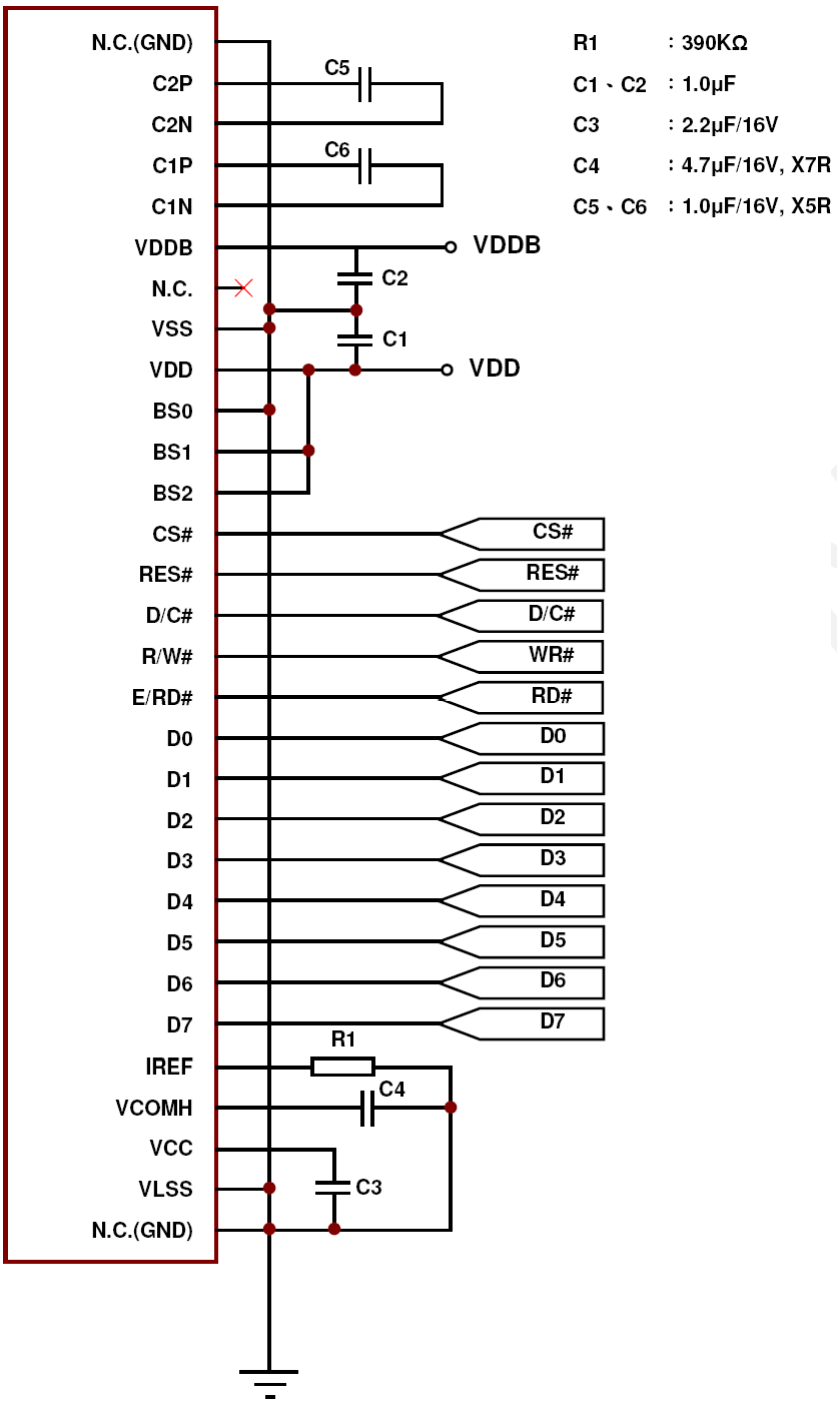
5.4.4 80XX-Series MPU Parallel Interface and VCC Generated by Internal DC/DC Circuit



R1	: 390KΩ
C1、C2	: 1.0μF
C3	: 2.2μF/16V
C4	: 4.7μF/16V, X7R
C5、C6	: 1.0μF/16V, X5R

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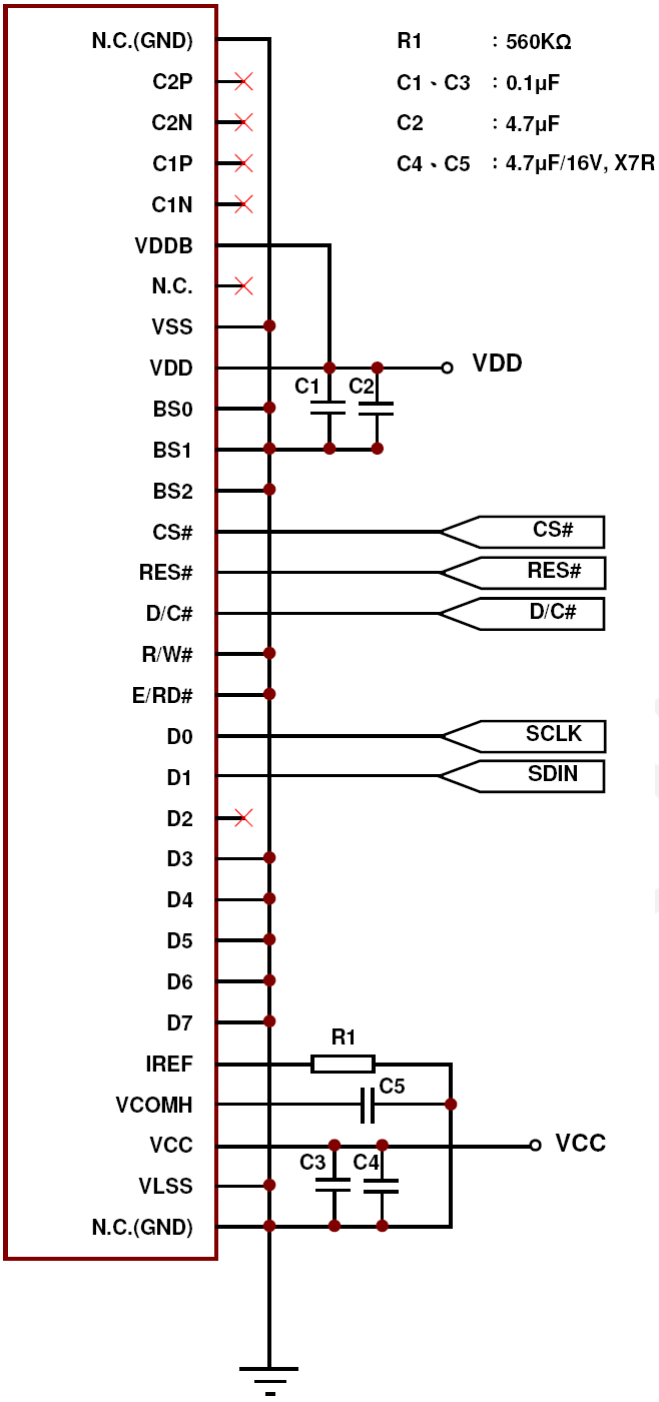
5.4.5 4-wire Serial Interface and VCC Supplied Externally



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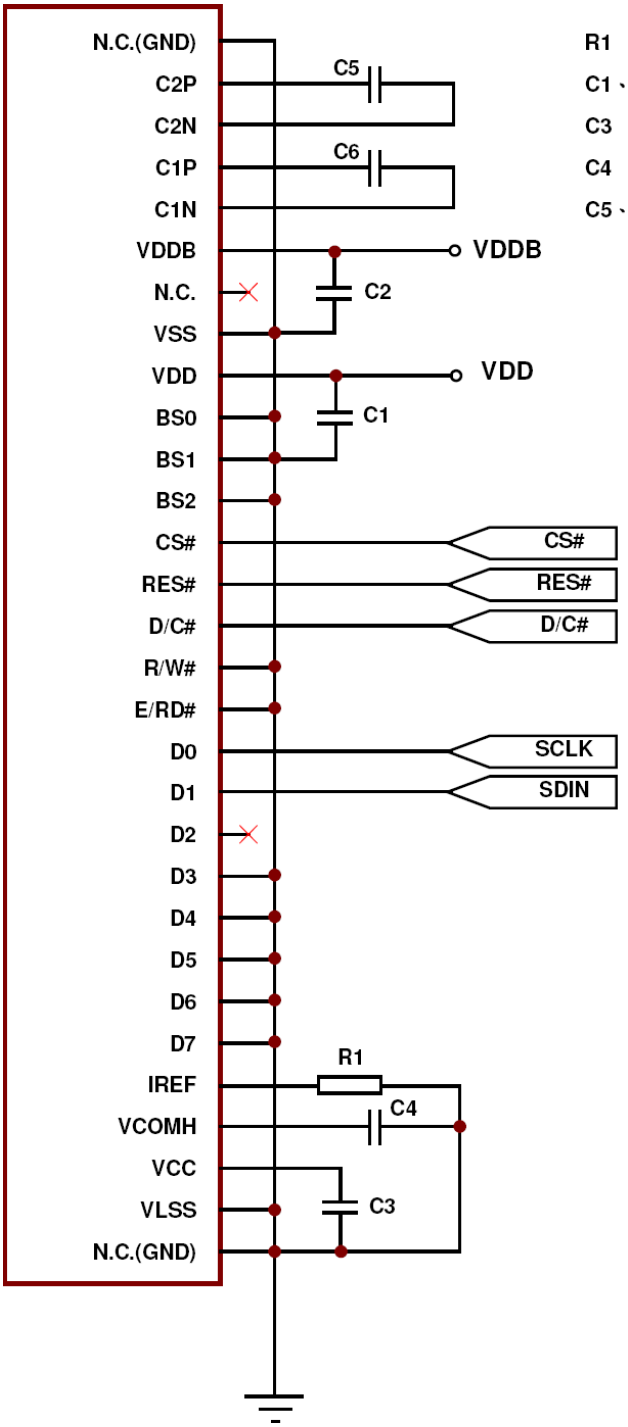
5.4.6 4-wire Serial Interface and VCC Generated by Internal DC/DC Circuit



R1 : 390KΩ
C1、C2 : 1.0μF
C3 : 2.2μF/16V
C4 : 4.7μF/16V, X7R
C5、C6 : 1.0μF/16V, X5R

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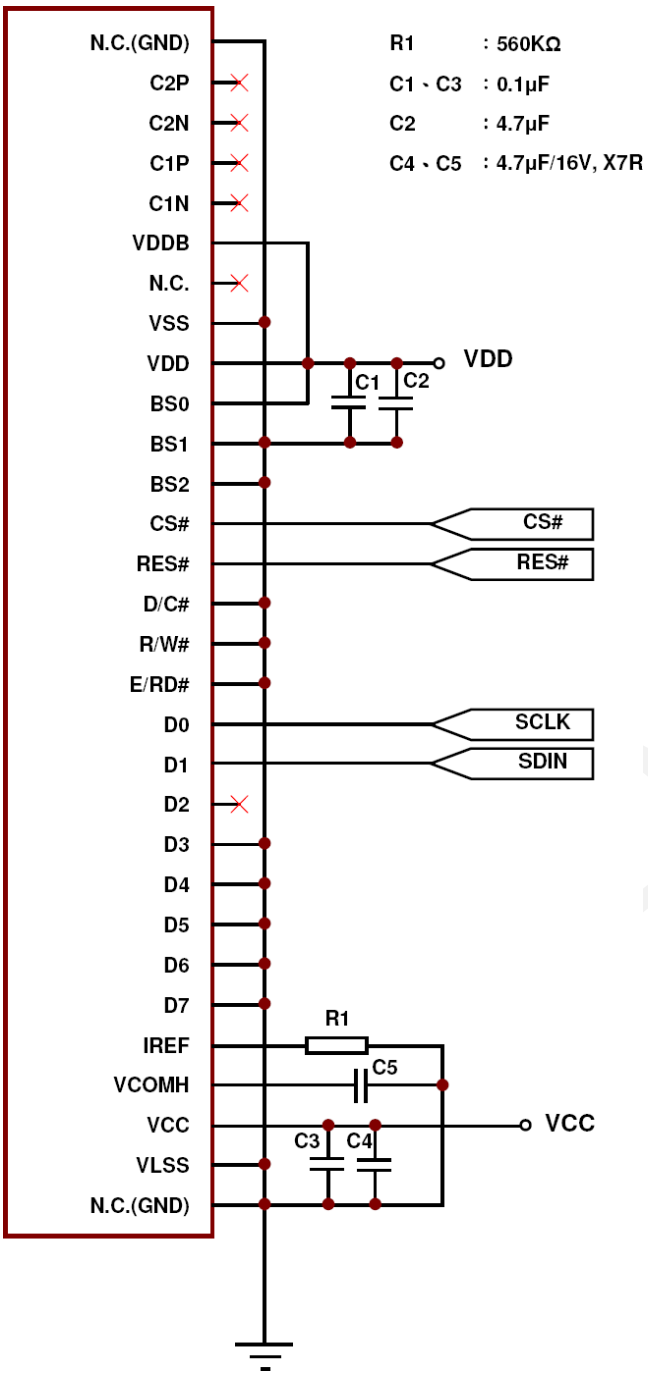
5.4.7 3-wire Serial Interface and VCC Supplied Externally



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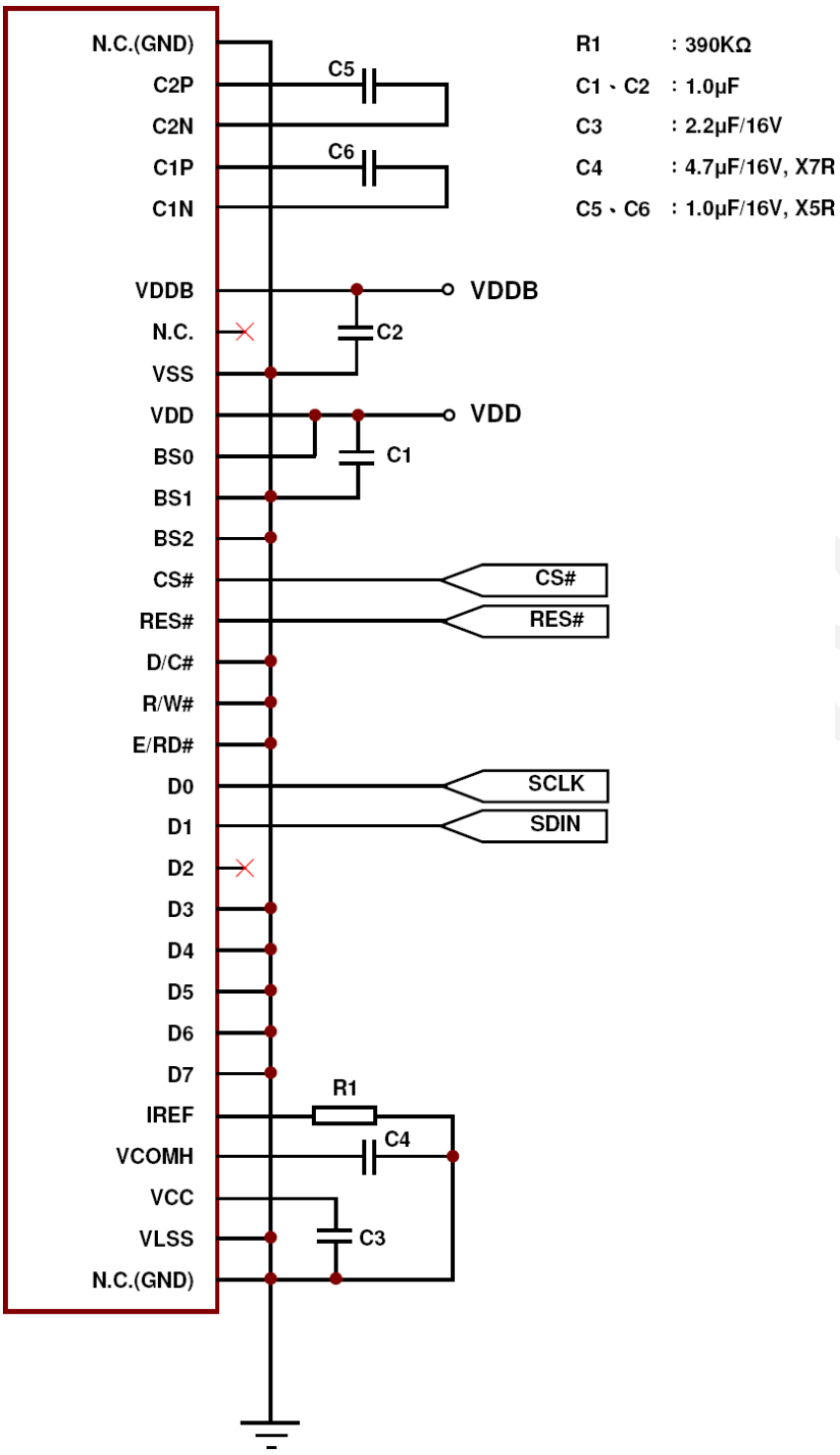
5.4.8 3-wire Serial Interface and V_{CC} Generated by Internal DC/DC Circuit



R1 : 390KΩ
C1、C2 : 1.0μF
C3 : 2.2μF/16V
C4 : 4.7μF/16V, X7R
C5、C6 : 1.0μF/16V, X5R

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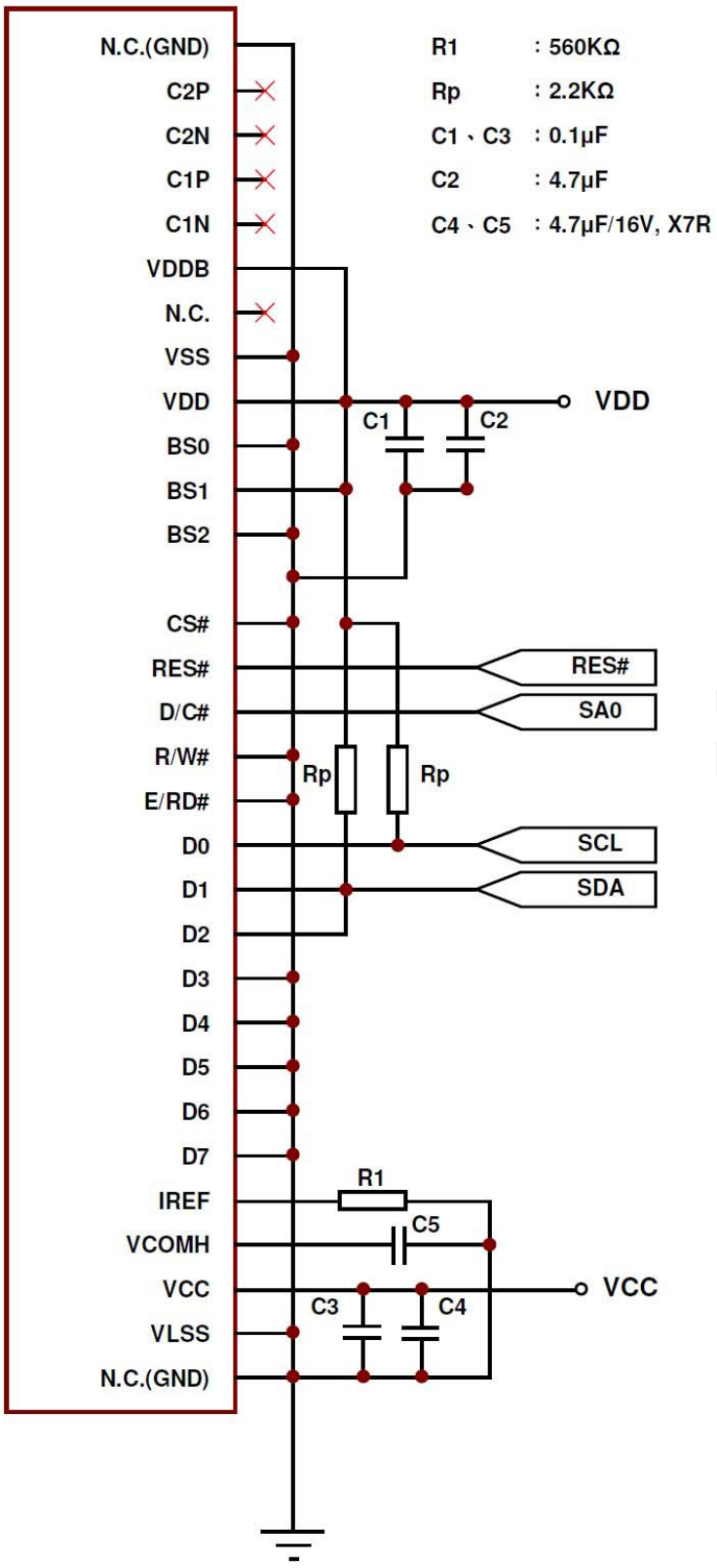
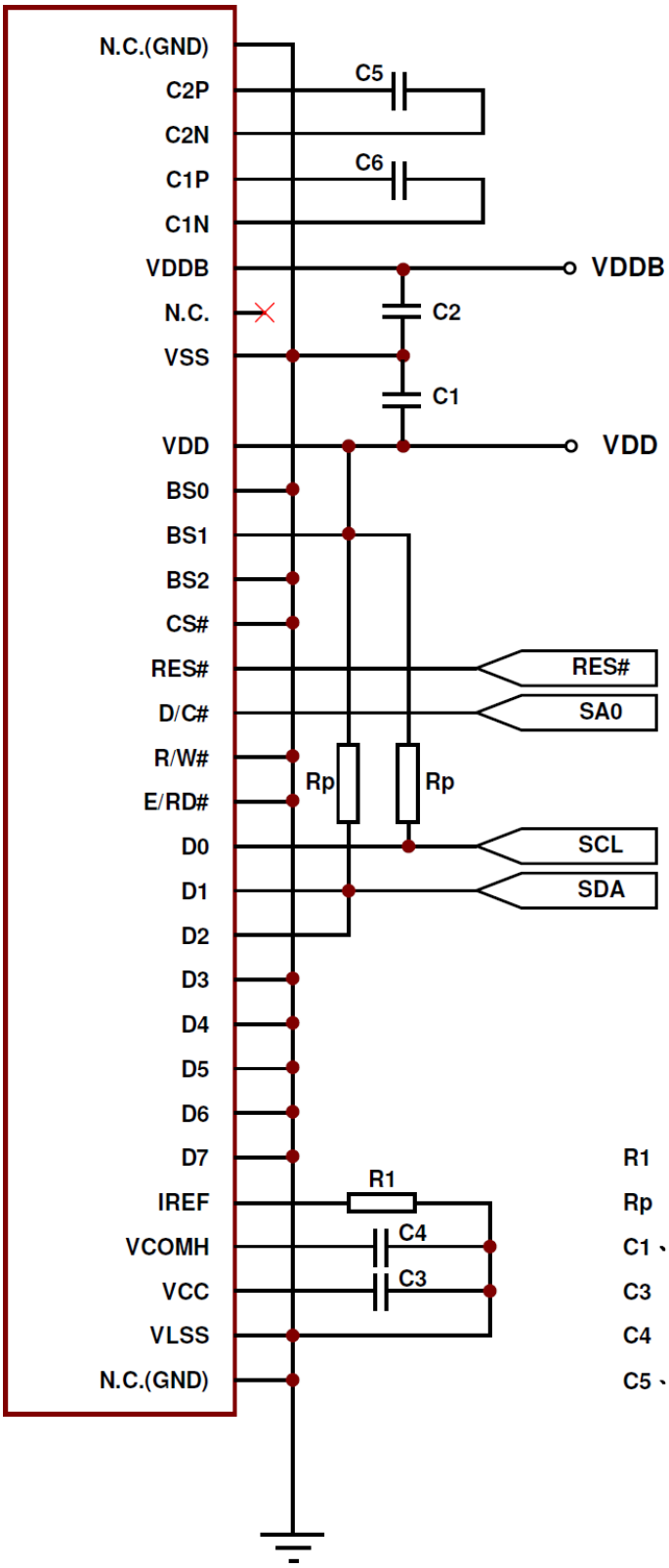
5.4.9 I²C Interface and VCC Supplied Externally



5.4.10 I2C Interface and VCC Generated by Internal DC/DC Circuit



R1	: 390KΩ
Rp	: 2.2KΩ
C1、C2	: 1.0μF
C3	: 2.2μF/16V
C4	: 4.7μF/16V, X7R
C5、C6	: 1.0μF/16V, X5R

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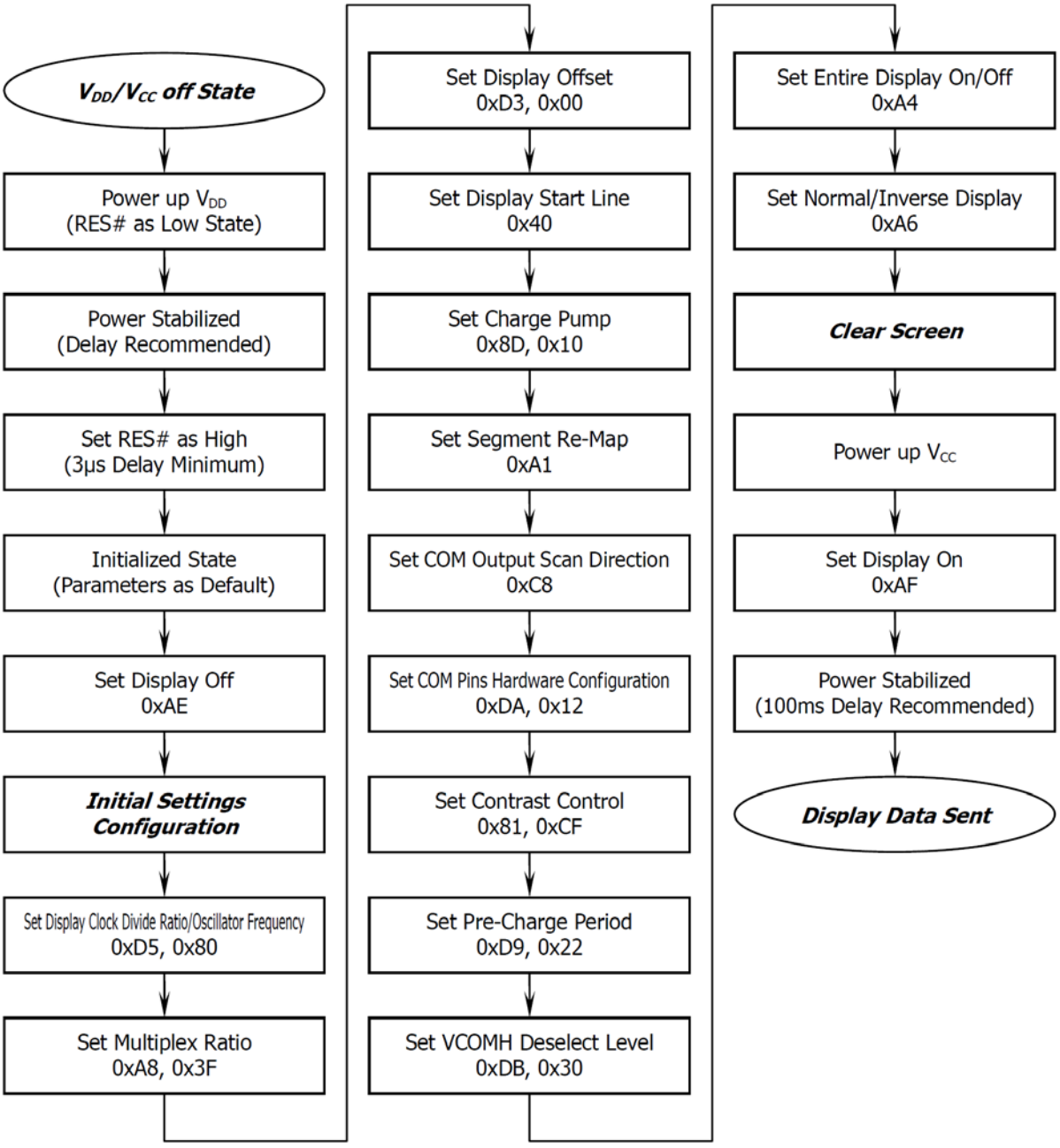
5.5 Actual Application Example OLED

Command usage and explanation of an actual example

5.5.1 V_{CC} Supplied Externally

<Power up Sequence>



If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

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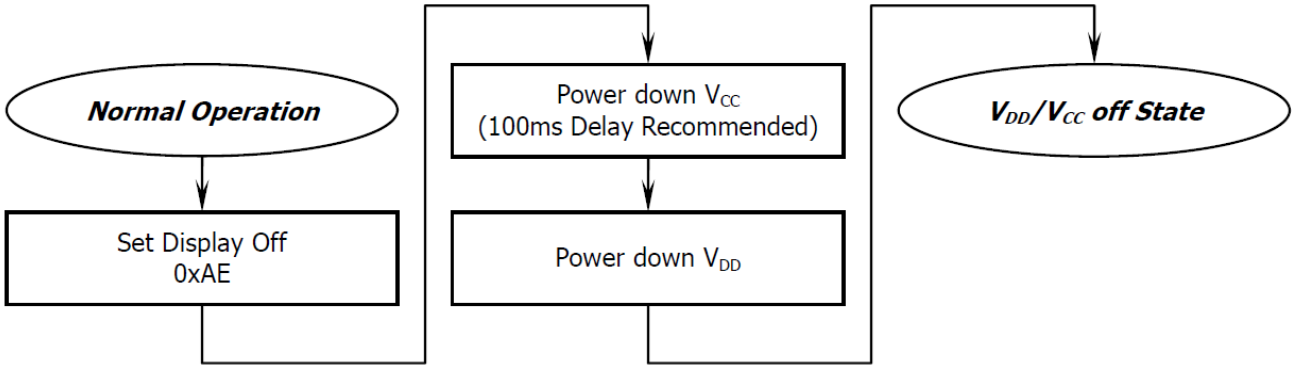
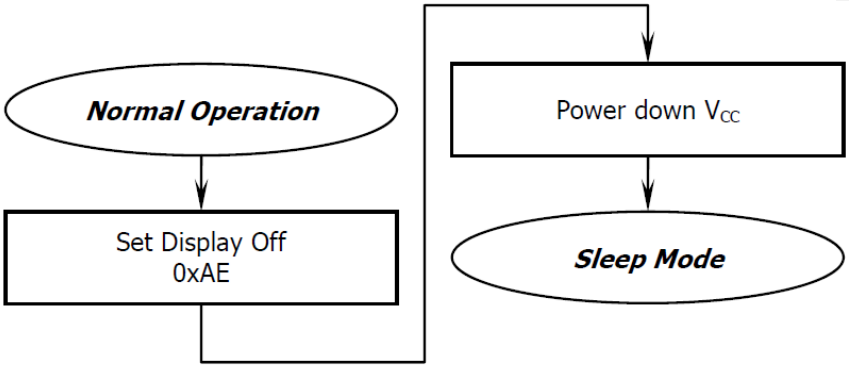
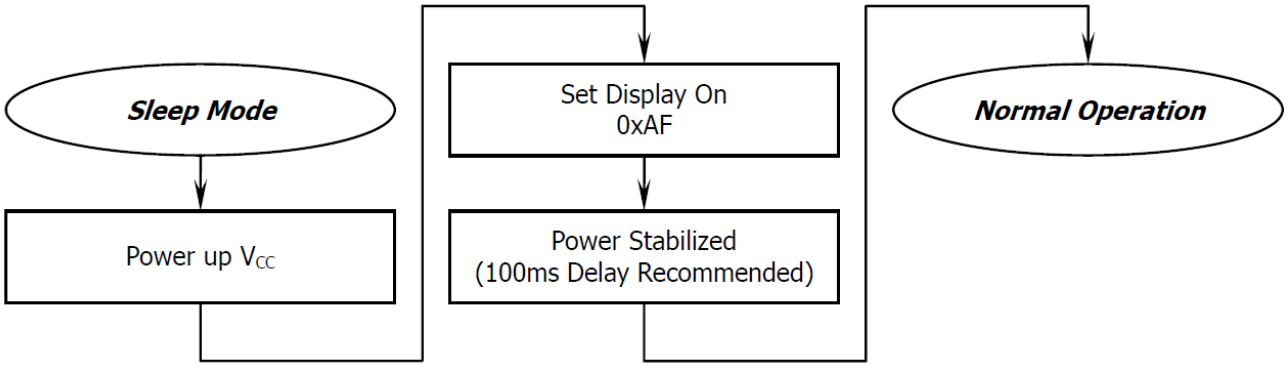
<Power down Sequence>



<Entering Sleep Mode>



<Exiting Sleep Mode>



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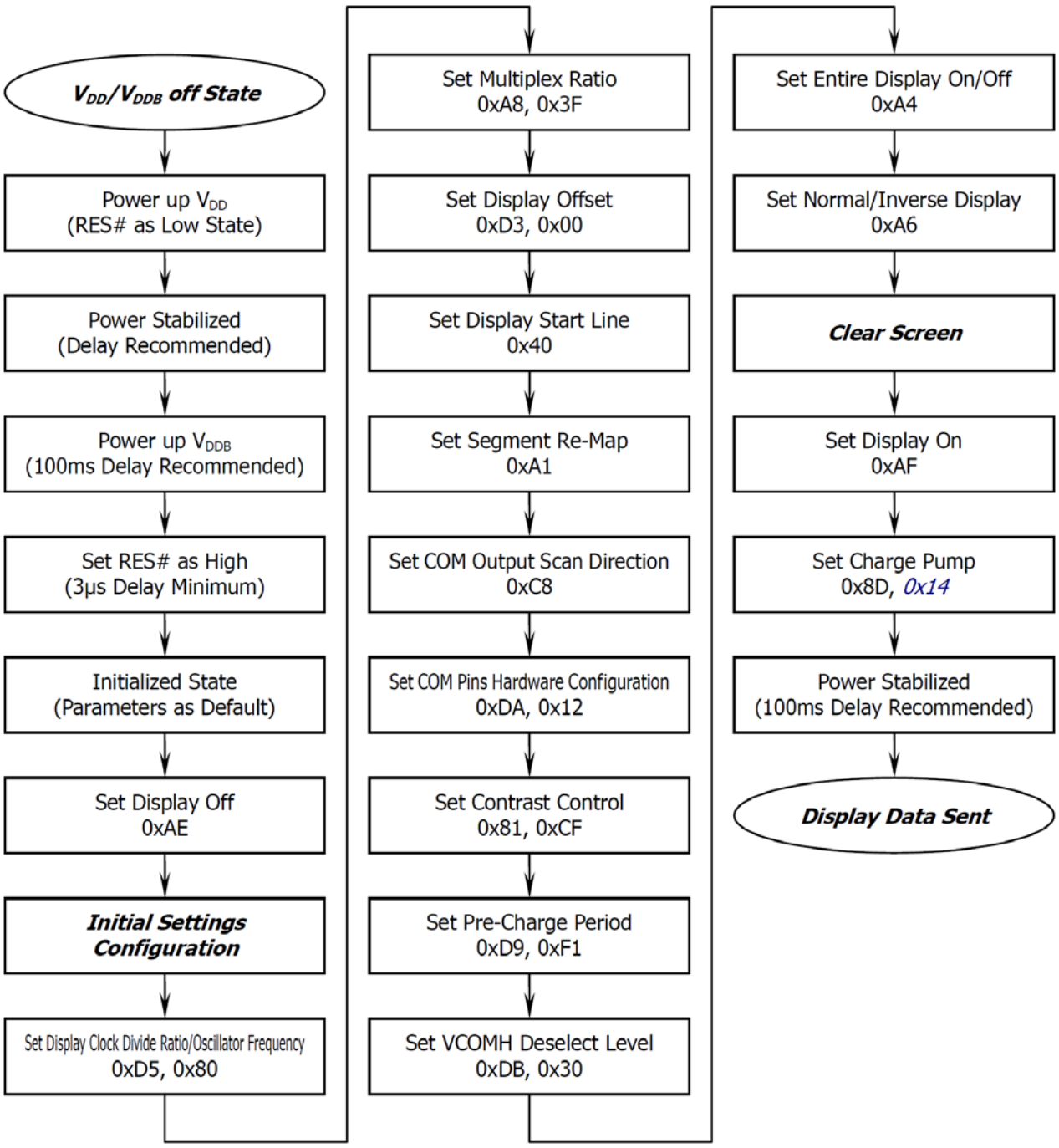
5.5.2 V_{CC} Generated by Internal DC/DC Circuit

<Power up Sequence>



If the noise is accidentally occurred at the displaying window during the operation, please reset the display in order to recover the display function.

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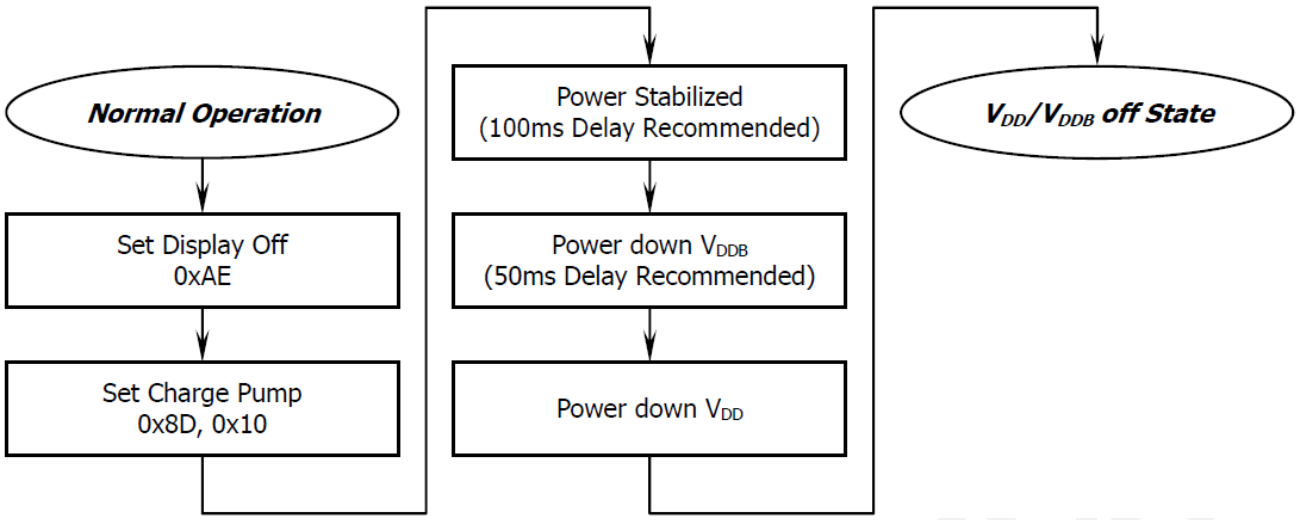
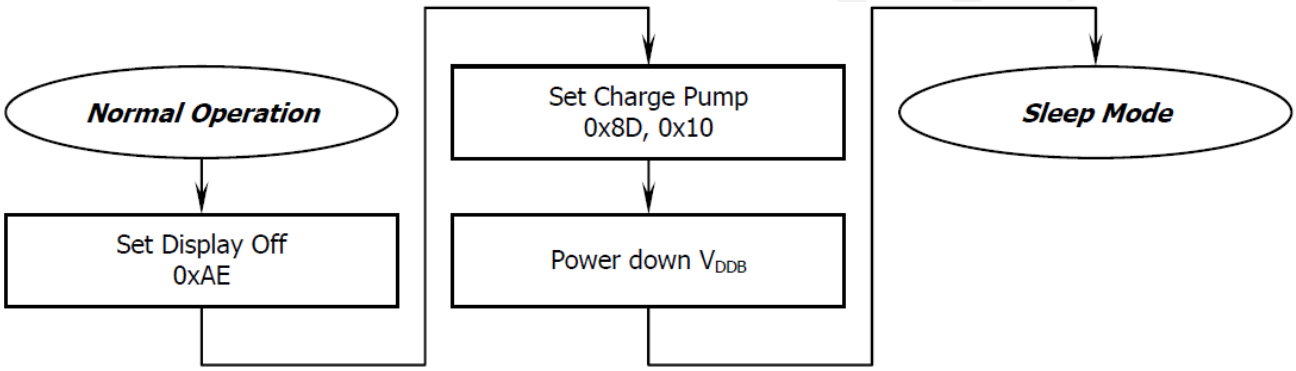
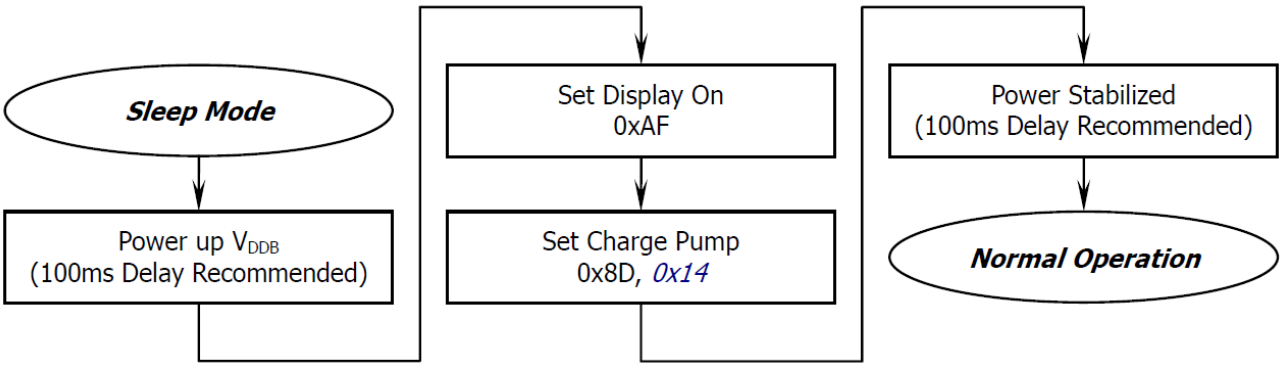
<Power down Sequence>



<Entering Sleep Mode>



<Exiting Sleep Mode>



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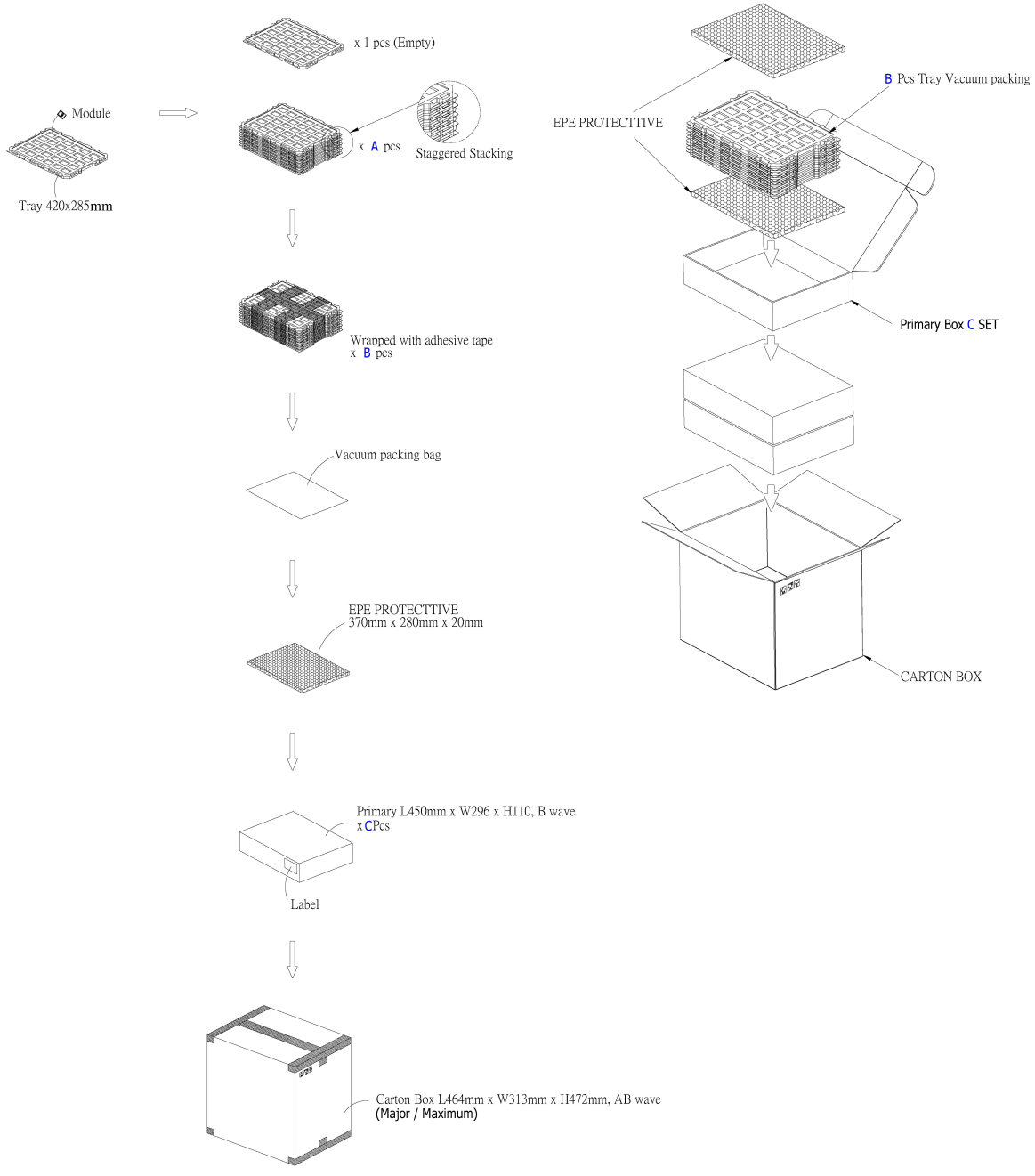
6. Packaging



Item	Quantity
Module	1080 per Primary Box
Holding Trays (A)	20 per Primary Box
Total Trays (B)	21 per Primary Box (Including 1 Empty Tray)
Primary Box (C)	1~4 per Carton (4 as Major / Maximum)

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7. Quality Assurance Specification

7.1 Conformity

The performance, function and reliability of the shipped products conform to the Product Specification.

7.2 Environment Required

Customer's test & measurement are required to be conducted under the following conditions:

Temperature:	23 ± 5°C
Humidity:	55% ± 15% RH
Fluorescent Lamp:	30W
Distance between the Panel & Lamp:	≥ 50cm
Distance between the Panel & Eyes of the Inspector:	≥ 30cm

Finger glove (or finger cover) must be worn by the inspector.

Inspection table or jig must be anti-electrostatic.

7.3 Delivery Assurance

7.3.1 Delivery Inspection Standards

Level II, Normal Inspection, Single Sampling, MIL-STD-105E

7.3.2 Criteria & Acceptable Quality Level

Partition	AQL	Definition
Major	0.65	Defects in Pattern Check (Display On)
Minor	1.0	Defects in Cosmetic Check (Display Off)

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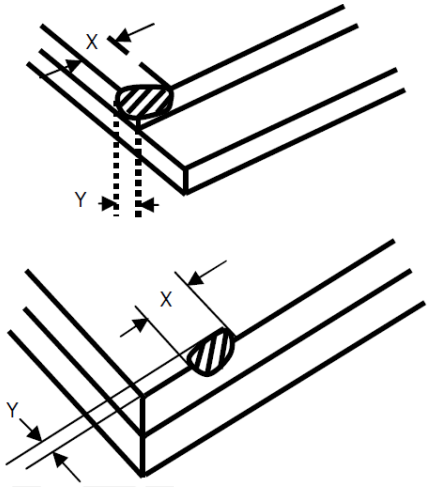
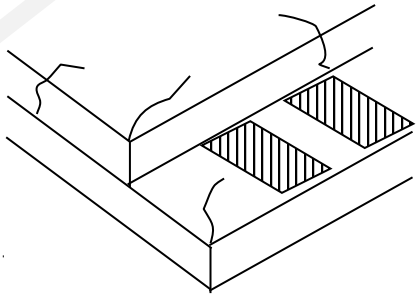
7.3.2.1 Cosmetic Check (Display Off) in Non-Active Area

Check Item	Classification	Criteria
Panel General Chipping	Minor	X > 6 mm (Along with Edge) Y > 1 mm (Perpendicular to edge) 
Panel Crack	Minor	Any crack is not allowable 
Copper Exposed (Even Pin or Film)	Minor	Not Allowable by Naked Eye Inspection
Film or Trace Damage	Minor	

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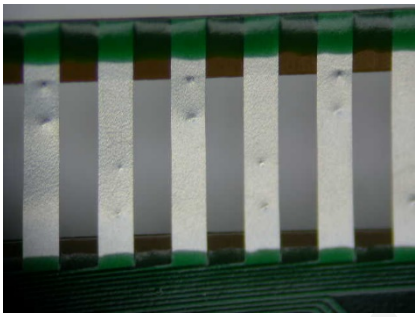
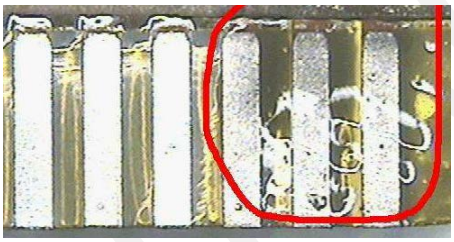
Check Item	Classification	Criteria
Terminal Lead Prober Mark	Acceptable	
Glue or Contamination on Pin (Couldn't Be Removed by Alcohol)	Minor	
Ink Marking on Back Side of panel (Exclude on Film)	Acceptable	Ignore for Any

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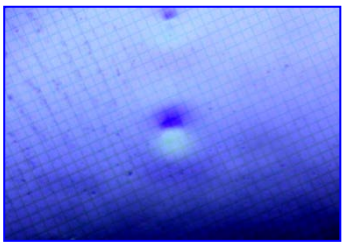
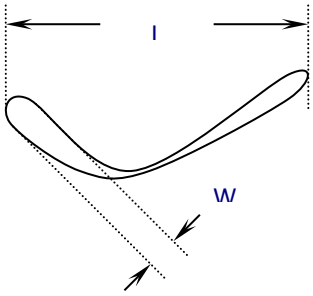
7.3.2.2 Cosmetic Check (Display Off) in Active Area

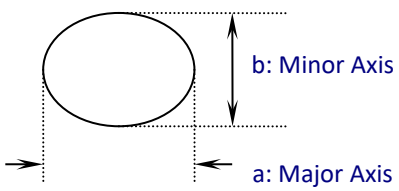
It is recommended to execute in clear room environment (class 10k) if actual in necessary.

Check Item	Classification	Criteria	
Any Dirt & Scratch on Polarizer's Protective Film	Acceptable	Ignore for not Affect the Polarizer	
Scratches, Fiber, Line-Shape Defect (On Polarizer)	Minor	W ≤ 0.1 W > 0.1, L ≤ 2 L > 2	Ignore n ≤ 1 n = 0
Dirt, Black Spot, Foreign Material (On Polarizer)	Minor	Φ ≤ 0.1 0.1 < Φ ≤ 0.25 0.25 < Φ	Ignore n ≤ 1 n = 0
Dent, Bubbles, White spot (Any Transparent Spot on Polarizer)	Minor	Φ ≤ 0.5 0.5 < Φ	➔ Ignore if no Influence on Display n = 0
			
Fingerprint, Flow Mark (On Polarizer)	Minor	Not Allowable	

Note 1: Protective film should not be tear off when cosmetic check.

Note 2: Definition of W & L & Φ (Unit: mm): Φ = (a + b) / 2





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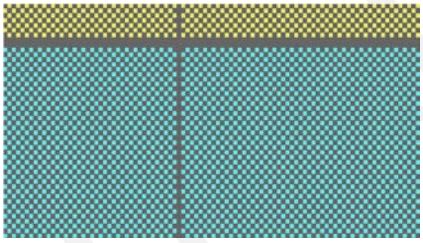
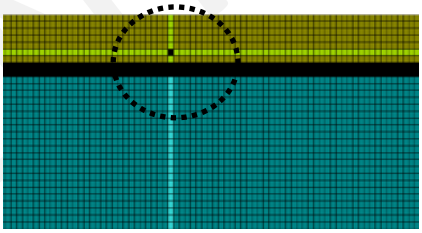
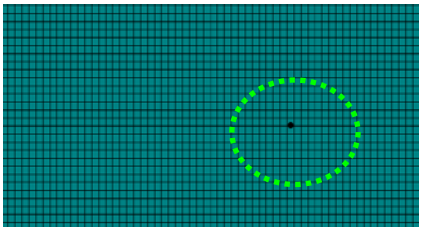
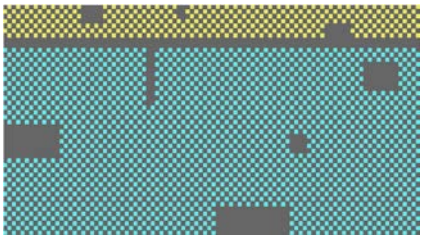
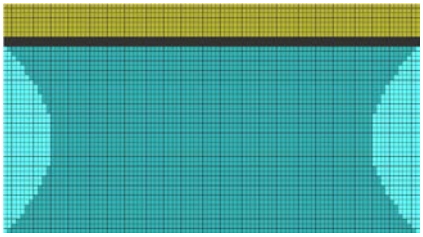
7.3.2.3 Pattern Check (Display On) in Active Area

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Pixel	Major	
Wrong Display	Major	
Un-uniform	Major	

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7.4 Dealing with Customer Complaints

7.4.1 Non-conforming Analysis

Purchaser should supply Densitron with detailed data of non-conforming sample.

After accepting it, Densitron should complete the analysis in two weeks from receiving the sample.
If the analysis cannot be completed on time, Densitron must inform the purchaser.

7.4.2 Handling of Non-conforming Displays

If any non-conforming displays are found during customer acceptance inspection which Densitron is clearly responsible for, return them to Densitron.
Both Densitron and customer should analyse the reason and discuss the handling of non-conforming displays when the reason is not clear.
Equally, both sides should discuss and come to agreement for issues pertaining to modification of Densitron quality assurance standard.

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8. Reliability Specification

8.1 Reliability Tests

Test Item	Test Condition	Inspection After Test
High Temperature Operating	70℃, 240 hrs	The operational functions work.
Low Temperature Operating	-40℃, 240 hrs	
High Temperature Storage	85℃, 240 hrs	
Low Temperature Storage	-40℃, 240 hrs	
High Temperature & High Operating	+60℃, 90% RH, 120 hours.	
Thermal Shock (Non-operation)	-40℃ ↔ 85℃, 24 Cycles, 60 min dwell.	

Note 1: The samples used for the above tests do not include polarizer.

Note 2: No moisture condensation is observed during tests.

8.1.1 Failure Check Standard

After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure teat at 23±5 °C；55±15% RH.

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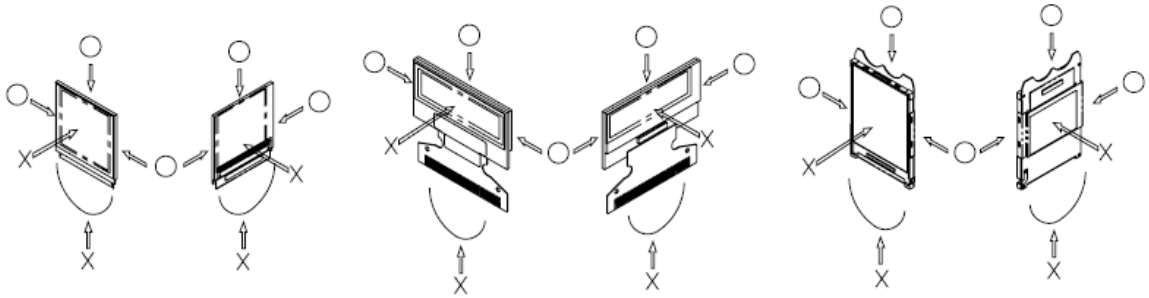
9. Handling Precautions

9.1 Handling Precautions

1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
3) If pressure is applied to the display surface or its neighborhood of the OEL display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
4) The polarizer covering the surface of the OEL display module is soft and easily scratched. Please be careful when handling the OEL display module.
5) When the surface of the polarizer of the OEL display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
   a. Scotch Mending Tape No. 810 or an equivalent
   b. Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent such as ethyl alcohol, since the surface of the polarizer will become cloudy.
   c. Also, pay attention that the following liquid and solvent may spoil the polarizer:
      - Water
      - Ketone
      - Aromatic Solvents
6) Hold OEL display module very carefully when placing OEL display module into the system housing. Do not apply excessive stress or pressure to OEL display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient



rigidity for the outer cases.
7) Do not apply stress to the LSI chips and the surrounding molded sections.
8) Do not disassemble nor modify the OEL display module.
9) Do not apply input signals while the logic power is off.
10) Pay sufficient attention to the working environments when handing OEL display modules to prevent occurrence of element breakage accidents by static electricity.

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- Be sure to make human body grounding when handling OEL display modules.
- Be sure to ground tools to use or assembly such as soldering irons.
- To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- Protective film is being applied to the surface of the display panel of the OEL display module. Be careful since static electricity may be generated when exfoliating the protective film.

11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OEL display module has been stored for a long period of time, residue adhesive material of the protection film may remain on the surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5).
12) If electric current is applied when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

9.2 Storage Precautions

1) When storing OEL display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps, etc. and, also, avoiding high temperature and high humidity environments or low temperature (less than 0°C) environments. (We recommend you to store these modules in the packaged state when they were shipped from Densitron Technologies Plc.) At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
2) If electric current is applied when water drops are adhering to the surface of the OEL display module, when the OEL display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

9.3 Designing Precautions

1) The absolute maximum ratings are the ratings which cannot be exceeded for OEL display module, and if these values are exceeded, panel damage may be happen.
2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)
4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.
5) As for EMI, take necessary measures on the equipment side basically.
6) When fastening the OEL display module, fasten the external plastic housing section.

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7) If power supply to the OEL display module is forcibly shut down by such errors as taking out the main battery while the OEL display panel is in operation, we cannot guarantee the quality of this OEL display module.
8) The electric potential to be connected to the rear face of the IC chip should be as follows: US2066

*Connection (contact) to any other potential than the above may lead to rupture of the IC.

9.4 Operation Precautions

1) When an OEL display module is operated for a long of time with fixed pattern may remain as an after image or slight contrast deviation may occur. Nonetheless, if the operation is interrupted and left unused for a while, normal state can be restored. Also, there will be no problem in the reliability of the module.
2) To protect OEL display modules from performance drops by static electricity rapture, etc., do not touch the following sections whenever possible while handling the OEL display modules.
   a. Pins and electrodes
   b. Pattern layouts such as the FPC
3) With this OEL display module, the OEL driver is being exposed. Generally speaking, semiconductor elements change their characteristics when light is radiated according to the principle of the solar battery. Consequently, if this OEL driver is exposed to light, malfunctioning may occur.
   a. Design the product and installation method so that the OEL driver may be shielded from light in actual usage.
   b. Design the product and installation method so that the OEL driver may be shielded from light during the inspection processes.
4) Although this OEL display module stores the operation state data by the commands and the indication data, when excessive external noise, etc. enters into the module, the internal status may be changed. It therefore is necessary to take appropriate measures to suppress noise generation or to protect from influences of noise on the system design.
5) We recommend you to construct its software to make periodical refreshment of the operation statuses (re-setting of the commands and re-transference of the display data) to cope with catastrophic noise.

9.5 Other Precautions

1) Request the qualified companies to handle industrial wastes when disposing of the OEL display modules. Or, when burning them, be sure to observe the environmental and hygienic laws and regulations.

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